

POS	SPECIFICATION	DOCUMENT#	REMARK
1	Valid for ED-type product family with or without TIM	DRW 0044	Outline drawing ST-type products
2	RoHS compliant		YES
3	Weight		340 g ± 20 g

POS	CONSTRUCTION ELEMENT	MATERIAL GROUP	MATERIALS	CAS-NR IF APPLICABLE	AVERAGE MASS ¹ IN %	COMMENT
1	Chip	Inorganic material	Silicon	7440-21-3	0.2	
2	Baseplate, substrate, incl. metallization	Non noble metal	Copper	7440-50-8	57.2	
3		Inorganic	Aluminum oxide	1344-28-1	1.8	
4		Non noble metal	Tin	7440-31-5	1.9	
5		Noble metal	Silver	7440-22-4		Traces
6		Non noble metal	Nickel	7440-02-0	0.3	Traces
7	Wire	Non noble metal	Aluminum	7429-90-5	0.3	
8		Non noble metal	Copper	7440-50-8	0.1	
9	Encapsulation	Polymer	Silicone gel		10.5	
10		Polymer	Silicon glue		0.3	
11	Housing	Polymer	PBT		10.5	
12		Inorganic material	Glas fiber		4.5	
13	Power & signal terminals incl plating, nuts, and rivets	Non noble metal	Copper	7440-50-8	11.2	
14		Ferrous metal	Steel		2.8	
15		Non noble metal	Nickel	7440-02-0		Traces
16		Non noble metal	Zinc	7440-66-6		Traces
17		Non noble metal	Tin	7440-31-5		Traces
18					100	Total %

REMARKS

- The information provided is the full declaration of all materials present in SwissSEM product of ED-type product family above a threshold of 0.1% or 1000 ppm.
- All information is according to the best of our knowledge and subject to change at any time for required changes.
- SwissSEM products are not classified as “hazardous substances” according to the definition of EU directive 67/548/EC and do hence not require a Material Safety Datasheet.

DATE	AUTHOR	REMARK
May 4th, 2023	SM	Initial Version

¹ Related to component weight

AUTHOR	CHECKED	RELEASED
PL	VP Application and Testing	VP Supply and Quality